TPC8207

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TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSIII)

TPC8207

Lithium Ion Battery Applications Notebook PC Applications Portable Equipment Applications

- Small footprint due to small and thin package
- Low drain-source ON resistance: R_{DS} (ON) = 16 m Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 11 \text{ S (typ.)}$
- Low leakage current: $I_{DSS} = 10 \ \mu A (max) (V_{DS} = 20 \ V)$
- Enhancement-mode: $V_{th} = 0.5 \sim 1.2 \text{ V} (V_{DS} = 10 \text{ V}, I_D = 200 \text{ }\mu\text{A})$

Maximum Ratings (Ta = 25°C)

Cha	racteristics	Symbol	Rating	Unit	
Drain-source vo	Itage	V _{DSS}	20	V	
Drain-gate volta	ge (R _{GS} = 20 kΩ)	V _{DGR}	20	V	
Gate-source vol	tage	V _{GSS}	±12	V	
Drain current	DC (Note 1)	۱ _D	6	А	
	Pulse (Note 1)	I _{DP}	24	~	
Drain power dissipation	Single-device operation (Note 3a)	P _{D (1)}	1.5		
(t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	P _{D (2)}	1.1	W	
Drain power dissipation	Single-device operation (Note 3a)	P _{D (1)}	0.75	w	
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.45		
Single pulse avalanche energy (Note 4)		E _{AS}	46.8	mJ	
Avalanche curre	nt	I _{AR}	6	А	
Repetitive avala Single-device va (Note 2a, 3b, 5)	nche energy alue at dual operation	E _{AR}	0.1	mJ	
Channel temper	ature	T _{ch}	150	°C	
Storage tempera	ature range	T _{stg}	-55~150	°C	



Weight: 0.08 g (typ.)

Circuit Configuration



Note: (Note 1), (Note 2), (Note 3), (Note 4), (Note 5) Please see next page.

This transistor is an electrostatic sensitive device. Please handle with caution.

Unit: mm

Thermal Characteristics

Characteristics	Symbol	Max	Unit		
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	83.3	°C/W	
	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	114		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R _{th (ch-a)} (1)	167		
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	278	°C/W	

Marking (Note 6)



Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:

a) Device mounted on a glass-epoxy board (a)





b) Device mounted on a glass-epoxy board (b)

FR-4 25.4 × 25.4 × 0.8 (Unit: mm)



Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.).
- b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.).

Note 4: $V_{DD} = 16 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$ (initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = 6 A

- Note 5: Repetitive rating; pulse width limited by max channel temperature.
- Note 6: on lower right of the marking indicates Pin 1. * shows lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: January to December are denoted by letters A to L respectively)

Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS}=\pm 10~V,~V_{DS}=0~V$			±10	μA
Drain cut-OFF cu	rain cut-OFF current		$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			10	μA
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$ 20		_	_	V
Diam-source bie	n-source breakdown voltage		$I_D = 10 \text{ mA}, V_{GS} = -12 \text{ V}$	8	_	_	v
Gate threshold vo	oltage	V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 200 \mu\text{A}$	0.5	_	1.2	V
			$V_{GS} = 2.0 \text{ V}, I_D = 4.2 \text{ A}$		22	45	
Drain-source ON resistance		R _{DS (ON)}	$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 4.2 \text{ A}$		19	30	mΩ
			$V_{GS} = 4.0 \text{ V}, I_D = 4.8 \text{ A}$		16	20	
Forward transfer admittance		Y _{fs}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 3.0 \text{ A}$	5.5	11		S
Input capacitance		C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	2010		pF
Reverse transfer capacitance		C _{rss}			210		
Output capacitance		C _{oss}		_	240		
Switching time	Rise time	t _r	$V_{GS} \begin{array}{c} 5 \\ 0 \\ V \end{array} \begin{array}{c} \\ \\ 0 \\ V \end{array} \begin{array}{c} \\ \\ \\ \\ \\ \\ \end{array} \begin{array}{c} \\ \\ \\ \\ \\ \\ \\ \end{array} \begin{array}{c} \\ \\ \\ \\ \\ \\ \\ \end{array} \begin{array}{c} \\ \\ \\ \\ \\ \\ \\ \\ \end{array} \begin{array}{c} \\ \\ \\ \\ \\ \\ \\ \\ \end{array} \begin{array}{c} \\ \\ \\ \\ \\ \\ \\ \\ \end{array} \begin{array}{c} \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \end{array} \begin{array}{c} \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \end{array} \begin{array}{c} \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \end{array} \begin{array}{c} \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\$	_	6	_	- ns
	Turn-ON time	t _{on}		_	14	_	
	Fall time	t _f		_	22	_	
	Turn-OFF time	t _{off}			94	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	22	_	
Gate-source charge 1		Q _{gs1}	$V_{DD} \simeq 16 \text{ V}, \text{ V}_{GS} = 5 \text{ V}, \text{ I}_{D} = 6 \text{ A}$		3.2		nC
Gate-drain ("miller") charge		Q _{gd}	1	_	4.7		

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	—		_	24	А
Forward voltage (diode)		V _{DSF}	$I_{DR} = 6 \text{ A}, V_{GS} = 0 \text{ V}$	_		-1.2	V

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Drain-source voltage V_{DS} (V)

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